

CHIPLINK N-Channel Enhancement Mode Power MOSFET



Maximum Ratings(T_A=25°C unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±10	V
Continuous Drain Current	I _D	2.3	A
Pulsed Drain Current ^B	I _{DM}	12	A
Maximum Power Dissipation ^A	PD	0.7	W
Junction and Storage Temperature Range	TJ, TSTG	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction to Ambient	R _{QJA}	162	°C/W

Electrical Characteristics (T_A=25 $^{\circ}$ Cunless otherwise specified)

Parameter	Symbol	Test conditions	MIN	TYP	MAX	UNIT
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	20			V
Gate-Threshold Voltage	V _{th(GS)}	V_{DS} = V_{GS} , I_D =250 uA	0.4	0.65	1.1	V
Gate-body Leakage	IGSS	V_{DS} =0V, V_{GS} =±10V			±100	nA
Zero Gate Voltage Drain Current	IDSS	V_{DS} =20V, V_{GS} =0V			1	uA
Drain-Source On-Resistance	Б	V _{GS} =4.5V, I _D =2.5A		45	60	mΩ
	TOS(ON)	V _{GS} =2.5V, I _D =2.0A		55	90	mΩ
Forward Transconductance	g fs	V _{DS} =5V, I _D =1.0A	2			S
Dynamic Characteristics						
Input Capacitance	Ciss			260		pF
Output Capacitance	Coss	$V_{DS} = 10V, V_{GS} = 0V,$ F=1MH7		48		
Reverse Transfer Capacitance	C _{rss}			27		
Switching Capacitance						
Turn-on Delay Time	t _{d(on)}	V _{DD} = 10V, R _L =2.9Ω		2.5		nS
Turn-on Rise Time	tr			3.2		nS
Turn-off Delay Time	t _{d(off)}	V_{GS} = 4.5V, R_{GEN} =3 Ω		21		nS
Turn-off Fall Time	t _f			3.0		nS
Total Gate Charge	Qg	V _{DS} = 10V. I _D =2A.		2.9		nC
Gate-Source Charge	Q _{gs}	V _{GS} =4.5V		0.4		nC
Gate-Drain Charge	Q _{gd}			0.6		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _D =5A			1.2	V
Diode Forward Current	ls				2.0	Α

Notes:

- A. The Power dissipation P_D is based on $T_{J(MAX)}$ =150 °C, using≤10s junction-to ambient thermal resistance.
- B. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150℃.Ratings are based on low frequency and duty cycles to keep initial T_J=25℃.
- C. The Static characteristics in Figures are obtained using $\langle 300 \ \mu \ s \ pulses$, duty cycle 2% max.



Typical Electrical and Thermal Characteristics



Figure 1:Switching Test Circuit











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Figure 14 Normalized Maximum Transient Thermal Impedance



SOT-23 Package Information







Cumula al	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
e	0.950 TYP.		0.037 TYP.		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF.		0.022 REF.		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

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